

We Claim:

1. A semiconductor device module comprising:

a semiconductor device including:

a multi-layer wiring board which comprises insulation layers and circuit pattern layers laminated alternately and is provided with a three-dimensional wiring comprising said circuit pattern layers provided on both sides of the insulation layer and a plurality of inner via holes penetrating through each of said insulation layers and electrically connecting;

at least a first semiconductor element mounted on the one side of the multi-layer wiring board and a second semiconductor element mounted on the other side of said multi-layer wiring board wherein electrodes of said semiconductor elements are connected with each other by means of said three-dimensional wiring; and

a mother multi-layer wiring board having a circuit pattern formed on said surface thereof, wherein

said semiconductor device is mounted on said mother multi-layer wiring board and said semiconductor device and said mother multi-layer wiring board are connected by electrical connection means.

2. The module of the semiconductor device according to claim 1, wherein said electrical connection means is a projecting electrode which is interposed between said multi-layer wiring board of said semiconductor device and said mother multi-layer wiring board by bonding said back surface of said second semiconductor element onto said mother multi-layer wiring board thus placing said semiconductor device on said mother multi-layer wiring board, thereby to connect said circuit pattern provided on said multi-layer wiring board and said circuit pattern provided on said mother multi-layer wiring board.

3. The module of the semiconductor device according to claim 1, wherein said electrical connection means is an electrically conductive supporting body which is electrically connected to said wiring in said multi-layer wiring board of said semiconductor device and is also used to fasten said semiconductor device onto said mother multi-layer wiring board, so as to establish electrical connection between said wiring of said multi-layer wiring board of said semiconductor device and said circuit pattern

provided on said mother multi-layer wiring board by fastening said semiconductor device onto said mother multi-layer wiring board via said electrically conductive supporting body.